

DOCKET NO. CHITTIPEDDI 59-108



PATENT

Gp 2823

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Sailesh Chittipeddi, et al.

Serial No.: 09/467,253

Filed: December 20, 1999

For: WIRE BONDING METHOD FOR COPPER INTERCONNECT
IN SEMICONDUCTOR DEVICES

Group No.: 2823

Examiner: Estrada, Michelle

#22
Prior Art
FJONES
10-25-02

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Commissioner for Patents
Washington, D. C. 20231

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on 9-18-02 (Date)
Elizabeth Schumacher
(Printed or typed name of person signing the certificate)
Elizabeth Schumacher
(Signature of the person signing the certificate)
9-18-02
(Date of Signature)

Sir:

INFORMATION DISCLOSURE STATEMENT

In accordance with 37 C.F.R. §1.56 and the provisions of 37 C.F.R. §§1.97 and 1.98 and §609 of the Manual of Patent Examining Procedure, Applicant hereby makes a disclosure of the patents, publications and other information listed below and on the accompanying form PTO-1449, which may be potentially material to the patentability of the invention disclosed in the above-referenced application. Pursuant to § 1.97(e) the Applicant hereby states that each item of information contained in the information disclosure statement was cited in a communication from

a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement.

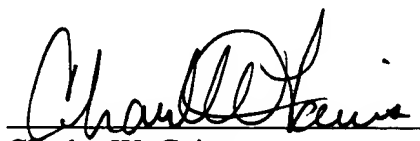
<u>U.S. Patent No.</u>	<u>Inventor</u>	<u>Date</u>
5,785,236	Cheung et al.	July 28, 1998
<u>Foreign Patent No.</u>	<u>Country</u>	<u>Date</u>
EP 1 022 776 A2	EP	26 July 2000
WO 01/01478 A1	WO	22 June 2000
EP 0 849 797 A2	EP	24 June 1998
JP 5-251494	JP	28 September 1993
JP 0 365 919	EP	2 May 1990

Applicant hereby certifies that each item of information contained in the Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the statement.

As attorney for the Applicant, I am signing below on the basis of the information supplied by an individual designated in § 1.56(c).

Respectfully submitted,

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